



Software Engineering in Practice (SEIP) Call for Papers

Theme:

Silicon Valley is home to many of the world's largest technology corporations and is a global hub for high-tech innovation and development. ICSE 2013's proximity to Silicon Valley creates an unprecedented opportunity for collaboration between industry and academia. The Software Engineering in Practice (SEIP) track provides a dedicated forum for practitioners to share ideas, advice, and solutions to real software development problems. To that end, SEIP seeks papers that highlight industrial challenges, breakthroughs, and case studies. SEIP especially seeks papers with high take-away value to help practitioners improve their own software engineering processes, techniques, and results. Also valuable are papers that help academics identify important new areas of research. Past innovations in Software Engineering have emerged from both industry and academia. ICSE provides a forum for networking, exchanging ideas, developing new visions within and between these communities that can impact the future directions of software engineering, and forging long-term partnerships designed to solve some of the most pressing and difficult problems of our field.

Scope:

- **Experience reports and case studies:** Each paper should provide clear take-away value by describing the context of a software engineering problem of practical importance; discussing why the solution of the problem is innovative, effective, or efficient; providing a concise explanation of the approach, techniques, and methodologies employed; and explaining the best practices that emerged, tools developed, and/or software processes involved. Furthermore, papers should describe broader applicability; overall assessment of benefits, risks and mitigations, and other lessons learned. 6-10 pages.

- **Panel proposals:** We solicit panel proposals on software engineering topics that are likely to be relevant and of interest to industrial attendees. Each proposal should describe the topic to be discussed, argue why the topic is timely and of interest, and identify an initial panel membership. 2 pages.

- **Mini tutorials:** Mini tutorials are 90 minute presentations on a particular software engineering topic for an industrial audience. Proposals should identify the topic, provide a biography of the tutorial presenter(s), outline why the topic is timely and relevant, and describe the content of the tutorial in sufficient detail to judge the relevance of the proposal. 2 pages.

Important Dates:

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|-----------------------|---------------------|
| Paper submission: | November 2, 2012 |
| Notifications: | January 25, 2013 |
| Camera Ready: | March 1, 2013 |
| ICSE 2013 SEIP Track: | 22nd-24th May, 2013 |

Submissions:

For submission instructions please refer to the ICSE 2013 website. Accepted papers will appear in the ICSE 2013 SEIP proceedings and the ACM and IEEE digital libraries.

SEIP Program Co-Chairs:

Jane Cleland-Huang, DePaul University, USA.
Erik Simmons, Intel Corporation, USA.

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- Dongmei Zhang, Microsoft, China;
- Jia Zhang, Carnegie Mellon Silicon Valley, USA

Inquiries:

If you have any questions concerning the scope of a topic or the submission and review process, please contact the organizers at: seipicse2013@easychair.org



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